

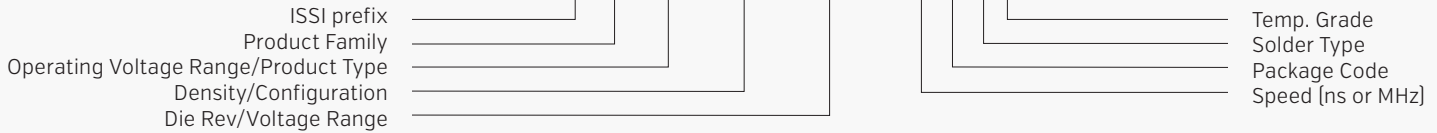


**THE DATASHEET OF  
IS61LV256-12TLI**



## SRAM Part Decoder

### IS 61 WV 12816 DBLL - 10 T L I



#### • SRAM Product Family

61/63 = High Speed  
 62 = Low Power  
 64 = Automotive High Speed  
 65 = Automotive Low Power  
 66 = Pseudo SRAM  
 67 = Automotive PSRAM

#### • Density/Configuration

Example:  
 25636 = 256Kx36  
 51216 = 512Kx16  
 1M36 = 1Mx36

#### • Die Rev/Voltage Range

Die Rev  
 Blank-Z

Voltage Range [WV]  
 ALL = 1.65V to 2.2V  
 BLL = 2.5V to 3.6V

#### • Operating Voltage Range/ Product Type

Asynchronous SRAM  
 C = 5V  
 LV = 3.3V  
 WV = Wide Voltage Range

Synchronous SRAM  
 P = Pipeline, F = Flowthrough  
 NLP/NLF/NVP/NVF = No-Wait Option  
 LP/LF: Vcc = 3.3V, VccQ = 3.3V/2.5V  
 VP/VF: Vcc = 2.5V, VccQ = 2.5V  
 QD = QUAD, DD = DDR-II Common I/O: Vcc = 1.8V, VccQ = 1.8V/1.5V

#### • Temp. Grade

Blank = Commercial Grade [ 0C to +70°C ]  
 I = Industrial Grade [ -40C to +85°C ]  
 A1 = Automotive Grade [-40C to +85°C]  
 A2 = Automotive Grade [-40C to +105°C]  
 A3 = Automotive Grade [-40C to +125°C]

#### • Solder Type

Blank = SnPb  
 L = Lead-free [RoHS Compliant]

#### • Package Code

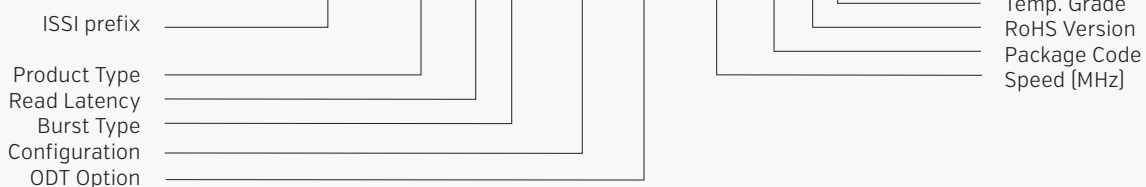
B, B1, B2, B3 = BGA  
 CT = Copper TSOP  
 H = sTSOP  
 J = 300-mil SOJ  
 K = 400-mil SOJ  
 LQ = LQFP  
 M, M3, = BGA  
 Q = SOP  
 T/T2 = TSOP  
 TQ = TQFP  
 U = SOP

#### • Speed [ns or MHz]

Example:  
 8 = 8ns  
 200 = 200MHz

## QUAD/P, DDR-II/P Part Decoder

### IS 61 QDP 2 B4 4M18 A1 - 333 M3 L I



#### • Product Type

QD = QUAD  
 QDP = QUADP  
 DD = DDR-II, Common I/O  
 DDP = DDR-IIP, Common I/O

#### • Configuration

51236 = 512Kb x 36  
 1M18 = 1Mb x 18  
 1M36 = 1Mb x 36  
 2M18 = 2Mb x 18  
 2M36 = 2Mb x 36  
 4M18 = 4Mb x 18

#### • Read Latency (RL):

For QUAD/DDR-II devices:  
 Blank = 1.5 clock cycles  
For QUADP/DDR-IIP devices:  
 Blank = 2.5 clock cycles  
 2 = 2.0 clock cycles

#### • Burst Type:

B2 = Burst 2  
 B4 = Burst 4

#### • ODT Option (if supported):

A: No ODT  
 A1: ODT Option 1  
 If ODT = HIGH or floating, a high range termination resistance is selected.  
 If ODT = LOW, a low range termination resistance is selected.  
 A2: ODT Option 2  
 If ODT = HIGH, a high range termination resistance is selected.  
 If ODT = LOW or floating, ODT is disabled

#### • Speed

Example: 250 = 250MHz

#### • Package Code

B4 = 165 ball BGA [13 x 15 mm]  
 M3 = 165-ball BGA [15 x 17 mm]

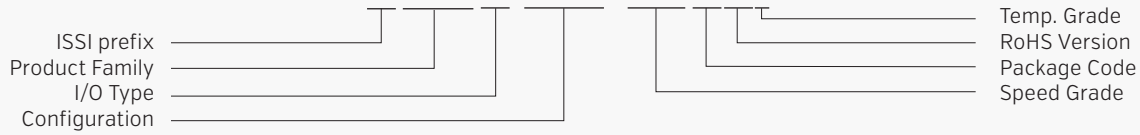
#### • RoHS Version

Blank = Leaded  
 L = Lead-free

#### • Temperature Range

Blank = Commercial [0C to 70°C]  
 I = Industrial [-40C to 85°C]

## IS49NL C 36800 - 25E B L I



• **Product Family:**

49NL = RLDRAM<sup>®</sup>2  
49RL = RLDRAM<sup>®</sup>3

• **I/O Type:**

C = Common I/O  
S = Separate I/O  
Blank = RLDRAM<sup>®</sup>3

• **Configuration**

288Mb  
93200 = 32M x 9  
18160 = 16M x 18  
36800 = 8M x 36  
576Mb  
96400 = 64M x 9  
18320 = 32M x 18 or 2M x 18 x 16 banks  
36160 = 16M x 36 or 1M x 36 x 16 banks  
1Gb  
18640 = 64M x 18  
36320 = 32M x 36

• **Speed Grade:**

25E - tCK = 2.5ns; tRC = 15ns  
25 - tCK = 2.5ns; tRC = 20ns  
33 - tCK = 3.3ns; tRC = 20ns  
5 - tCK = 5ns; tRC = 20ns  
093E - tCK = 0.93ns; tRC = 8ns  
093 - tCK = 0.93ns; tRC = 10ns  
107E - tCK = 1.07ns; tRC = 8ns  
107 - tCK = 1.07ns; tRC = 10ns  
125F - tCK = 1.25ns; tRC = 8ns  
125E - tCK = 1.25ns; tRC = 10ns  
125 - tCK = 1.25ns; tRC = 12ns

• **Package Code:**

B = 168-ball FBGA [RLDRAM<sup>®</sup>3]  
B = 144-ball FBGA [RLDRAM<sup>®</sup>2]

• **RoHS Version:**

Blank = SnPb  
L = Lead-free [RoHS compliant]

• **Temperature Range:**

Blank = Commercial [0C to 70°C]  
I = Industrial [-40C to 85°C]

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